

IN THE CLAIMS:

Please AMEND claims 1, 4, 7 and 11 as follows. A marked up copy of the claims is attached in Appendix A. For the Examiner's convenience, all claims currently pending in this application have been reproduced below:

91 1. (Three Times Amended) A substrate cutting method for cutting a substrate of a thin film semiconductor device constructed by adjacently arranging a plurality of substrates on substantially a same plane, on each of the substrates, two dimensionally arranged thin film semiconductor elements are installed comprising the steps of:

cutting a substrate having a slice line provided on a side of the substrate to be adjacent another substrate and a guide line provided on the substrate, which corresponds to the slice line and is different from the slice line; and

detecting a position of the guide line and correcting a cutting position while the substrate is cut along the slice line.

3. (Unamended) A method according to claim 1, wherein the guide line is provided on the substrate and the slice line and the guide line are simultaneously formed.

92 4. (Three Times Amended) A substrate cutting method for cutting a substrate of a thin film semiconductor device constructed by adjacently arranging a plurality of substrates on

42 substantially a same plane, on each of the substrates, two-dimensionally arranged thin film semiconductor elements are installed comprising the steps of:

cutting a substrate having a slice line provided on a side of the substrate to be adjacent another substrate and a guide line provided on the substrate, which corresponds to the slice line and is different from the slice line; and

detecting a position of the guide line and correcting a cutting position while the substrate is cut along the slice line,

wherein the guide line is an electrode line provided on the substrate.

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6. (Unamended) A method according to claim 1, wherein said cutting step is executed by a rotary blade.

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43 7. (Three Times Amended) A substrate cutting method for cutting a substrate of a thin film semiconductor device constructed by adjacently arranging a plurality of substrates substantially a same plane, on each of the substrates, two-dimensionally arranged thin film semiconductor elements are installed comprising the steps of:

cutting a substrate having an electrode layer provided on the substrate;

detecting, during the cutting, a position of a guide line provided corresponding to a slice line formed by the electrode layer on a side of the substrate to be adjacent another substrate; and correcting a cutting position based on the detection in said detecting step.

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8. (Unamended) A method according to claim 7, further comprising forming an electrode line on the substrate, wherein the electrode layer is formed by a same material as that of the electrode line formed on the substrate.

9. (Unamended) A method according to claim 7, further comprising forming an electrode line on the substrate and simultaneously forming the electrode layer with the electrode line formed on the substrate.

10. (Unamended) A method according to claim 1, wherein the slice line and the guide line are arranged in parallel.

94 11. (Three Times Amended) A substrate cutting method for cutting a substrate of a thin film semiconductor device constructed by adjacently arranging a plurality of substrates on substantially a same plane, on each of the substrates, two-dimensionally arranged thin film semiconductor elements are installed comprising the steps of:

cutting a substrate, provided with a slice line on a side of the substrate to be adjacent another substrate and a guide line, along the slice line of the substrate;

detecting the guide line during the cutting to detect deviation with respect to the guide line; and

correcting a cutting position based on the detected deviation.